

II. AMENDMENTS TO THE CLAIMS

Please cancel claims 8 and 9 and enter the claim amendments specified below. A complete listing of all claims in the Application is provided below along with the claim's status, which is indicated in a parenthetical expression after each claim number. For claim amendments, deleted matter is indicated by strike-out text and added matter is indicated by underlined text.

Claim 1 (currently amended) An electroplating solution for plating tin-copper alloy solder coatings comprising:

a sulfonic acid electrolyte;
a tin compound soluble in the sulfonic acid to form a tin sulfonate;
a copper compound soluble in the sulfonic acid to form a copper sulfonate;
a non-ionic surfactant;
a satin brightener comprising an aromatic amine, a tertiary amine, or oxidized 1-phenyl-3-pyrazolidione; and
an antioxidant.

Claim 2 (original) The electroplating solution of claim 1 wherein the sulfonic acid electrolyte comprises an alkane or alkanol sulfonic acid containing 1-5 carbon atoms

Claim 3 (original) The electroplating solution of claim 1 wherein the sulfonic acid electrolyte comprises methanesulfonic acid.

Claim 4 (original) The electroplating solution of claim 1 wherein the tin compound comprises tin methanesulfonate.

Claim 5 (original) The electroplating solution of claim 1 wherein the copper compound comprises copper methanesulfonate.

Claim 6 (original) The electroplating solution of claim 1 wherein the non-ionic surfactant comprises polyethylene glycol.

Claim 7 (currently amended) The electroplating solution of claim 1 wherein the non-ionic surfactant comprises polyoxyethylenepolyoxyethylene-block-polyoxypropylene with molecular weight between 2000 and 10,000.

Claims 8-9 (canceled).

Claim 10 (original) The electroplating solution of claim 1 wherein the antioxidant comprises catechol.